串口通讯协议格式：

不同厂家探头的间隔，面积对测量会有影响，微调R1 R3值
TDS测量标准按小米TDS笔做比较

		TDS2_1	J3
		TDS2_2	1
			2
			2.54-2P立式

TDS1_1	J4
TDS1_2	1
	2
	2.54-2P立式

U2 XC6206P332MR

5V — 2 VIN — VOut 3 — 3.3V

C5 10uF
GND

GND

C1 10uF   C2 100nF
GND   GND

U1 TDS16

1	1	VPP	16	16
2	2		15	15
3	3		14	TDS1_2
4	4		13	TDS1_1
5	5		12	PDA
6	6	TDS2_16	11	PCL
7	7		10	RXD
8	8	TDS2_28	9	TXD

R1 430R 1%
R3 430R 1%

GND

P1 Header 5
调试接口

5		3.3V
4		VPP
3		PCL
2		PDA
1		GND

5V	J2
	1
	2
GND	2.54-2P立式

TXD	J1
RXD	1
	2
GND	3
	2.54-3P立式
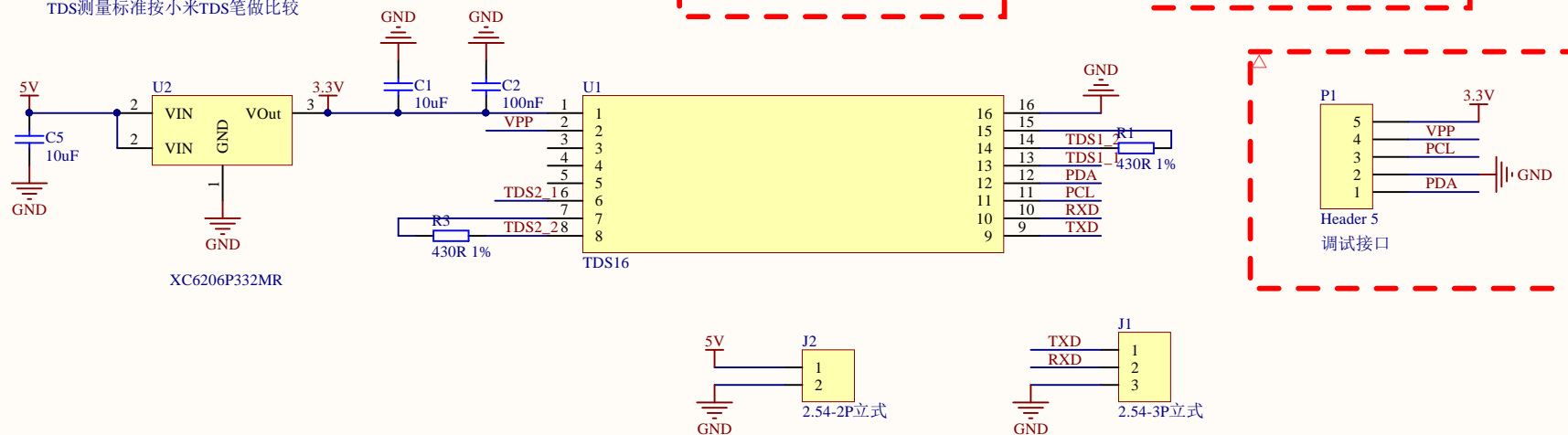
Title		
Size **A4**	Number	Revision
Date: 2020/11/20		Sheet of
File: E:\2020年 开发文件\..\Sheet1.SchDoc		Drawn By:

Comment	Description	Designator	Footprint	LibRef	Quantity
10uF		C1, C5	LC-0603_C	C0603	2
100nF		C2	LC-0603_C	C0603	1
2.54-3P立式		J1	3P2.54	2.54-3P立式	1
2.54-2P立式		J2, J3, J4	2P2.54	2.54-2P立式	3
Header 5	Header, 5-Pin	P1	HDR1X5	Header 5	1
430R 1%		R1, R3	LC-0603_R	R0603	2
TDS16		U1	LC-SOIC-16_150mil	TDS16	1
XC6206P332MR		U2	LC-SOT-23(SOT-23-3)	HT75XX_SOT89	1